

# CONSOLIDATED VERSION

# VERSION CONSOLIDÉE



**Semiconductor devices –  
Part 16-3: Microwave integrated circuits – Frequency converters**

**Dispositifs à semiconducteurs –  
Partie 16-3: Circuits intégrés hyperfréquences – Convertisseurs de fréquence**

IEC 60747-16-3:2002

<https://standards.iteh.ai/catalog/standards/iec/5aab671-7064-4c3c-9e6b-72f8946afd5f/iec-60747-16-3-2002>





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CONTENTS

FOREWORD..... 4

1 Scope..... 6

2 Normative references ..... 6

3 Terms and definitions ..... 6

4 Abbreviated terms ..... 8

5 Essential ratings and characteristics..... 9

5.1 General..... 9

5.2 Application description ..... 9

5.3 Specification of the function ..... 10

5.4 Limiting values (absolute maximum rating system) ..... 12

5.5 Operating conditions (within the specified operating temperature range) ..... 14

5.6 Electrical characteristics..... 14

5.7 Mechanical and environmental ratings, characteristics and data..... 15

5.8 Additional information..... 15

6 Measuring methods ..... 16

6.1 General..... 16

6.2 Conversion gain ( $G_C$ )..... 17

6.3 Conversion gain flatness ( $\Delta G_C$ ) ..... 19

6.4 LO/IF isolation ( $P_{LO} / P_{LO(IF)}$ )..... 21

6.5 LO/RF isolation ( $P_{LO} / P_{LO(RF)}$ )..... 22

6.6 RF/IF, IF/RF isolation ..... 24

6.7 Image rejection ( $P_O / P_{O(im)}$ )..... 28

6.8 Sideband suppression ( $P_O / P_{O(U)}$ )..... 29

6.9 Output power ( $P_O$ ) ..... 31

6.10 Output power at 1-dB conversion compression ( $P_{O(1dB)}$ ) ..... 32

6.11 Noise figure ( $F$ ) ..... 33

6.12 Intermodulation distortion ( $P_n/P_1$ )..... 35

6.13 Output power at the intercept point (for intermodulation products) ( $P_n(IP)$ ) ..... 38

6.14 LO port return loss ( $L_{ret(LO)}$ ) ..... 39

6.15 RF port return loss ( $L_{ret(RF)}$ ) ..... 40

6.16 IF port return loss ( $L_{ret(IF)}$ ) ..... 42

Bibliography..... 44

Figure 1 – Electrical terminal symbols..... 11

Figure 2 – Circuit diagram for the measurement of conversion gain ..... 17

Figure 3 – Circuit diagram for the measurement of the LO/IF isolation ..... 21

Figure 4 – Circuit diagram for the measurement of the LO/RF isolation..... 23

Figure 5 – Circuit diagram for the measurement of the RF/IF isolation for type A ..... 24

Figure 6 – Circuit diagram for the measurement of the ~~RF/IF~~ IF/RF isolation for type B ..... 26

Figure 7 – Circuit diagram for measurement of noise figure ..... 33

Figure 8 – Circuit for the measurement of intermodulation distortion ..... 36

Figure 9 – Circuit for the measurement of the LO port return loss ..... 39

Figure 10 – Circuit for the measurement of the RF/IF port return loss ..... 41

Table 1 – Function of terminals.....	11
Table 2 – Electrical limiting values.....	13
Table 3 – Electrical characteristics.....	15

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Part 16-3: Microwave integrated circuits –  
Frequency converters

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**In this Redline version, a vertical line in the margin shows where the technical content is modified by amendments 1 and 2. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.**



International Standard IEC 60747-16-3 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

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## SEMICONDUCTOR DEVICES –

### Part 16-3: Microwave integrated circuits – Frequency converters

#### 1 Scope

This part of IEC 60747 provides new measuring methods, terminology and letter symbols, as well as essential ratings and characteristics for integrated circuit microwave frequency converters.

#### 2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-702, *International Electrotechnical Vocabulary – Chapter 702: Oscillations, signals and related devices* (available at < <http://www.electropedia.org/>>)

IEC 60617, *Graphical symbols for diagrams* (available at < <http://std.iec.ch/iec60617> >)

~~IEC 60617-12, *Graphical symbols for diagrams – Part 12: Binary logic elements*~~

~~IEC 60617-13, *Graphical symbols for diagrams – Part 13: Analogue elements*~~

~~IEC 60747-1:1983, *Semiconductor devices – Discrete devices and integrated circuits – Part 1: General*~~

IEC 60747-1:2006, *Semiconductor devices – Part 1: General*  
IEC 60747-1:2006/AMD 1:2010

IEC 60748-2:1997, *Semiconductor devices – Integrated circuits – Part 2: Digital integrated circuits*

IEC 60748-3, *Semiconductor devices – Integrated circuits – Part 3: Analogue integrated circuits*

IEC 60748-4, *Semiconductor devices – Integrated circuits – Part 4: Interface integrated circuits*

IEC 61340-5-1:2007, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC/TR 61340-5-2:2007, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

#### 3 Terms and definitions

For the purpose of this part of IEC 60747, the following terms and definitions apply:

### 3.1

#### **conversion gain, $G_c$**

ratio of the desired converted output power to the input power

NOTE Usually, the conversion gain is expressed in decibels.

### 3.2

#### **conversion gain flatness, $\Delta G_c$**

difference between the maximum and the minimum conversion gain for a specified input power in a specified frequency range

### 3.3

#### **LO/RF isolation, $P_{LO}/P_{LO(RF)}$**

ratio of the incident local power to the local leakage power at the RF port with the IF port terminated in a specified impedance

### 3.4

#### **LO/IF isolation, $P_{LO}/P_{LO(IF)}$**

ratio of the incident local power to the local leakage power at the IF port with the RF port terminated in a specified impedance

### 3.5

#### **RF/IF isolation, $P_{RF}/P_{RF(IF)}$**

ratio of the incident RF power to the RF feedthrough power at the IF port for a specified local power

NOTE Usually, the RF/IF isolation is applied to the down-converter.

### 3.6

#### **IF/RF isolation, $P_{IF}/P_{IF(RF)}$**

ratio of the incident IF power to the IF feedthrough power at the RF port for a specified local power

NOTE Usually, the IF/RF isolation is applied to the up-converter.

### 3.7

#### **image rejection, $P_o/P_{o(im)}$**

ratio of the output power when the RF signal is applied, to the output power when the image signal is applied

NOTE Usually, the image rejection is applied to the down-converter.

### 3.8

#### **sideband suppression, $P_o/P_{o(U)}$**

ratio of the output power of the desired sideband to the output power of the undesired sideband

NOTE Usually, the sideband suppression is applied to the up-converter.

### 3.9

#### **LO port return loss, $L_{ret(LO)}$**

ratio of the specified incident power at the LO port to the reflected power at the LO port, with the RF port and the IF port terminated in each specified impedance

### 3.10

#### **RF port return loss, $L_{ret(RF)}$**

ratio of the incident power at the RF port to the reflected power at the RF port for a specified local power, with the IF port terminated in a specified impedance

**3.11**

**IF port return loss,  $L_{\text{ret}}(\text{IF})$**

ratio of the incident power at the IF port to the reflected power at the IF port for a specified local power, with the RF port terminated in a specified impedance

**3.12**

**output power**

$P_o$

~~see IEC 60747-16-2, 3.3<sup>1</sup>~~ RF power measured at the output port

[SOURCE: IEC 60747-4:2007/AMD1:2017, 7.2.2]

**3.13**

**output power at 1-dB conversion compression,  $P_{o(1\text{dB})}$**

output power where the conversion gain decreases by 1 dB compared with the linear conversion gain

**3.14**

**noise figure,  $F$**

~~see IEC 60747-1 Chapter IV, 5.4.4~~ see 702-08-57 of IEC 60050-702

NOTE The term "noise figure" expresses "noise factor" in decibels.

**3.15**

~~**intermodulation distortion,  $P_n/P_1$**~~

~~ratio of the output power of the  $n$ th order component to the output power of the fundamental component, at a specified input power~~

~~see 3.7 of Amendment 1 of IEC 60747-16-1~~

**intermodulation distortion**

$P_n/P_1$

ratio of the  $n$ th order component of the output power to the fundamental component of the output power

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NOTE The abbreviation " $IMD_n$ " is in common use for the  $n$ th order intermodulation distortion.

[SOURCE: IEC 60747-4:2007/AMD1:2017, 7.2.19]

**3.16**

**output power at the intercept point (for intermodulation products),  $P_n(\text{IP})$**

output power at the intersection between the extrapolated output powers of the fundamental component and the  $n$ th order intermodulation components, when the extrapolation is carried out in a diagram showing the output power of the components (in decibels) as a function of the input power (in decibels)

**4 Abbreviated terms**

The abbreviations used in this part of IEC 60747 are as follows:

- RF Radio Frequency;
- IF Intermediate Frequency;
- LO Local Oscillator.

<sup>1</sup> ~~IEC 60747-16-2:2001, Semiconductor devices – Part 16-2: Microwave integrated circuits – Frequency prescalers~~

## 5 Essential ratings and characteristics

### 5.1 General

This clause gives ratings and characteristics required for specifying integrated circuit microwave frequency converters.

#### 5.1.1 Circuit identification and types

##### 5.1.1.1 Designation and types

The identification of type (device name), the category of circuit and technology applied shall be given.

Microwave frequency converters are divided into two categories:

- type A: down-converter;
- type B: up-converter.

##### 5.1.1.2 General function description

A general description shall be made of the function performed by the integrated circuit microwave frequency converters and the features for the application.

##### 5.1.1.3 Manufacturing technology

The manufacturing technology, for example, semiconductor monolithic integrated circuit, thin film integrated circuit, micro-assembly, shall be stated. This statement shall include details of the semiconductor technologies such as Schottky-barrier diode, MESFET, Si bipolar transistor, HBT.

##### 5.1.1.4 Package identification

The following shall be stated:

- a) chip or packaged form;
- b) IEC and/or national reference number of the outline drawing, or ~~of~~ drawing of non-standard package including terminal numbering;
- c) principal package material, for example, metal, ceramic, plastic;
- d) for chip form: outlines, dimensions, pad sizes, contact material, and recommended contact technologies.

##### 5.1.1.5 Main application

The main application shall be stated if necessary. If the device has restrictive applications, these too shall be stated here.

### 5.2 Application description

Information on the application of the integrated circuit and its relation to the associated devices shall be given.

#### 5.2.1 Conformance to system and/or interface information

It shall be stated whether the integrated circuit conforms to an application system and/or an interface standard or recommendation.

Detailed information about application systems, equipment and circuits such as VSAT systems, DBS receivers, microwave landing systems shall also be given.

### 5.2.2 Overall block diagram

A block diagram of the applied systems shall be given if necessary.

### 5.2.3 Reference data

The most important properties required to permit comparison between derivative types shall be given.

### 5.2.4 Electrical compatibility

It shall be stated whether the integrated circuit is electrically compatible with other particular integrated circuits or families of integrated circuits, or whether special interfaces are required.

Details shall be given concerning the type of the input and output circuits, for example, input/output impedances, d.c. block, open-drain.

Interchangeability with other devices, if any, shall be given.

### 5.2.5 Associated devices

If applicable, mention shall be made here of

- devices necessary for correct operation (list with type number, name, and function);
- peripheral devices with direct interfacing (list with type number, name, and function).

## 5.3 Specification of the function

### 5.3.1 Detailed block diagram – functional blocks

A detail block diagram or equivalent circuit information of the integrated circuit microwave frequency converters shall be given. The block diagram shall be composed of the following:

- a) functional blocks;
- b) mutual interconnections among the functional blocks;
- c) individual functional units within the functional blocks;
- d) mutual interconnections among the individual functional blocks;
- e) function of each external connection;
- f) interdependence between the separate functional blocks.

The block diagram shall identify the function of each external connection, and, where no ambiguity can arise, it can also show the terminal symbols and/or numbers. If the encapsulation has metallic parts, any connection to them from external terminals shall be indicated. The connections with any associated external electrical elements shall be stated, where necessary.

For the purpose of providing additional information, the complete electrical circuit diagram can be reproduced, though this will not necessarily involve giving indications of the function. Rules governing such diagrams may be obtained from ~~IEC 60617-12 or IEC 60617-13~~ IEC 60617.

### 5.3.2 Identification and function of terminals

All terminals shall be identified on the block diagram (supply terminals, input or output terminals, input/output terminals).